

Data sheet Product ICK SMD H 25 MI



Heatsinks and active heatsinks for processors>Heatsinks for DIL-IC, PLCC and SMD

11.8 x 8 mm, for SMD components and others

Features

case type:	SMD
width:	11.8 mm
height:	8 mm
plate thickness:	2.5 mm
length:	25 mm
thermal resistance:	20 K/W
surface:	solderable surface

Technical Drawing

